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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/042,408	01/08/2002	Naoki Fukutomi	7426-082	9036
20457	7590	05/13/2004	EXAMINER	
ANTONELLI, TERRY, STOUT & KRAUS, LLP			BEREZNY, NEMA O	
1300 NORTH SEVENTEENTH STREET			ART UNIT	
SUITE 1800			PAPER NUMBER	
ARLINGTON, VA 22209-9889			2813	

DATE MAILED: 05/13/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

## Office Action Summary

Application No.

10/042,408

Applicant(s)

FUKUTOMI ET AL.

Examiner

Nema O Berezny

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 26 April 2004.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 14-21, 24, 25 and 27-37 is/are pending in the application.
- 4a) Of the above claim(s) 14-21 and 27-30 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 24, 25 and 31-37 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 28 August 2002 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)  | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftperson's Patent Drawing Review (PTO-948)                                    | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____  |

## DETAILED ACTION

### *Specification*

Cancellation of claims 22-23 and 26 in paper filed 4-26-04 is acknowledged.

### *Claim Rejections - 35 USC § 102*

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 25, 31-34, and 36-37 are rejected under 35 U.S.C. 102(e) as being anticipated by Marrs et al. (5,355,283). Marrs discloses a substrate for mounting semiconductor devices thereon having an insulating supporting member (Fig.2 el.202; col.7 lines 26-30) and plural sets of wirings (el.205), and further comprising: a semiconductor device mounting region (el.202) and a resin-sealing semiconductor package region (el.203) outside of said semiconductor device mounting region, wherein said plural sets of wirings comprise a predetermined wiring pattern including wire-bonding terminals (el.205) and external connection terminals (el.208), wherein said wire-bonding terminals are provided in said semiconductor package region and said external connection terminals are provided in said semiconductor device mounting region

(Fig.2), wherein said substrate includes a plurality of said semiconductor device mounting regions (col.4 line 66 – col.5 line 2), and wherein said plurality of said semiconductor device mounting regions respectively have blocks of said wirings, each having a same pattern (Fig.2) **[claim 32]**. Marrs also discloses wherein said external connecting terminals are exposed on a surface of said insulating supporting member, on opposite side of which said semiconductor device is mounted (Fig.2), and are arranged in a grid pattern at positions corresponding to said semiconductor device mounting region and said semiconductor packaging region (col.1 lines 25-35, 48-51) **[claim 25]**; wherein said wirings form a predetermined wiring pattern including a wire bonding terminal (el.205) and an external connection terminal (el.208); and said external connection terminal is provided only inside of said wire bonding terminal (Fig.2) **[claim 33]**; comprising a plurality of said wiring patterns comprised of a plurality of said wirings arranged in rows and columns (col.1 lines 25-35, 48-51) **[claim 34]**; and wherein said external connection terminal is one of a plurality of external connection terminals, exposed on a surface of said insulating supporting member, on an opposite side to which said semiconductor device is mounted, and said external connection terminals are arranged in a grid patterns at positions corresponding to a semiconductor device mounting region and a semiconductor package region of said substrate (col.1 lines 25-35, 48-51) **[claim 36]**. Marrs also discloses the semiconductor package (el.200) produced by a method comprising the steps of: mounting a semiconductor device on each of said plural semiconductor devices mounting regions of the substrate for mounting semiconductor device thereon according to claim 32 or 33 by employing a

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die bonding material; electrically connecting said semiconductor device with said wire-bonding terminal by wire-bonding; sealing said semiconductor package region including said plural semiconductor devices with a sealing resin connected in one-piece; forming solder bumps on said external connection terminals; and cutting said substrate for mounting semiconductor devices thereon and said sealing resin in one operation to be separated into the individual semiconductor package [claims 31, 37].

### ***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 24 and 35 are rejected under 35 U.S.C. 103(a) as being unpatentable over Marrs as applied to claims 32-33 above, and further in view of Katsuhiko (JP 59208756). Marrs discloses a gold plate layer (col.3 lines 60-63) on the surface of said wire-bonding terminal. However, Marrs does not disclose a nickel layer on said terminal. Katsuhiko discloses wherein said wire-bonding terminal is formed in said semiconductor packaging region, and said wire-bonding terminals comprise a nickel and gold plate layer on its surface (Constitution). Therefore, it would have been obvious to a person skilled in the art at the time of the invention to use the nickel plated wiring structures of Katsuhiko with the substrate of Marrs, in order to protect the terminal and facilitate wire bonding.

***Response to Arguments***

Applicant's arguments with respect to claims 22-26 and 31 have been considered but are moot in view of the new ground(s) of rejection.

***Conclusion***

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nema O Berezny whose telephone number is (571) 272-1686. The examiner can normally be reached on M-F 8:30-5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

NB

*Craig A. Thompson*  
**CRAIG A. THOMPSON**  
**PRIMARY EXAMINER**